Abstract

This invention relates to a method for bonding of a first contact area (3) of a first at least largely transparent substrate (1) to a second contact area (4) of a second at least largely transparent substrate (2), on at least one of the contact areas an oxide being used for bonding, from which an at least largely transparent interconnection layer (14) is formed with:

- an electrical conductivity of at least 10el S/cm^2 (measurement: four point method, relative to temperature of 300K) and
- an optical transmittance greater than 0.8 (for a wavelength range from 400 nm to 1500 nm) on the first and second contact area (3, 4).

Figure in this regard